

1.0 INTRODUCTION

This document describes the requirements for procuring the unpackaged integrated circuit die used in the manufacture of part number OP-05 which is an Operational Amplifier. All changes and/or substitutions to the procured parts are subject to prior approval by Interpoint. This specification is to be used with GEN-008.

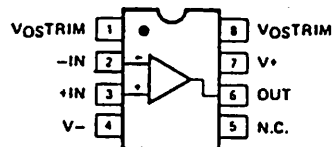
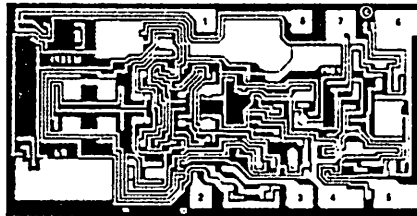
2.0 APPLICABLE DOCUMENTS

GEN-008 Integrated Circuit Dice

3.0 REQUIREMENTS

3.1 Mechanical/Physical Characteristics

Each die shall be configured as shown in Figure 1.



FOR REFERENCE ONLY

NOTES:

1. Mfr. Precision Monolithics, Inc. (PMI)
2. Die size .101 x .052 ± .005
3. Backside: Silicon or Gold

FIGURE 1 - DIE CONFIGURATION

3.2 Electrical Characteristics

Each die shall be tested by probing and meet the performance requirements specified in Table I.

99126-003

**interpoint**

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SIZE <b>A</b>	CAGE NO. <b>50821</b>	DRAWING NO. 84523	REV <b>B</b>
SCALE		SHEET 2 OF 3	